Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	238880	fluorine	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:37
S2	60677	hydrofluoric or (ammonium adj fluoride) or (tetramethylammonium adj fluoride)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:04
S3	286862	S1 or S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:39
S4	30429	high near (constant or k or permittivity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:44
S5	2913	S3 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:40
S6	1907236	etch or (wet adj etch) or remove	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:40
S7	1954	S5 and S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:40
S8	261065	((oxalic or citric or malonic or succinic or acetic or propionin) adj acid) and organic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:04
S9	174641	((sulfuric or nitric or hydrochloric or phosphoric or sulfamic) adj acid) and inorganic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:04

S10	275	S7 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:42
S11	275	S7 and S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:42
S12	148	S10 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:43
S14	1	10/793900	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:53
S15	90342	"ZrO.sub.2", "Ta.sub.2O.sub.5", "Nb.sub.2O.sub.5", "Al.sub.2O.sub. 3", "HfO.sub.2", HfSiON, "TiO.sub. 2", "ScO.sub.3", "Y.sub.2O.sub.3", "La.sub.2O.sub.3", "Ce.sub.2O.sub. 3", "Pr.sub.2O.sub.3", "Nd.sub.2O. sub.3", "Sm.sub.2O.sub.3", "Eu.sub. 2O.sub.3", "Gd.sub.2O.sub.3", "Tb. sub.2O.sub.3", "Dy.sub.2O.sub.3", "Ho.sub.2O.sub.3", "Er.sub.2O.sub. 3", "Tm.sub.2O.sub.3", "Yb.sub.2O. sub.3", "Lu.sub.2O.sub.3",	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:48
S16	36	S12 and S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 11:50
S17	1554578	zirconium, tantalum, aluminum, hafnium, niobium, titanium, yttrium, scandium, lanthanides	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:05
S18 _.	139	S12 and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:00

S19	36287	S2 and S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:04
S20	394336	((oxalic or citric or malonic or succinic or acetic or propionin) adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:04
S21	506932	((sulfuric or nitric or hydrochloric or phosphoric or sulfamic) adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:04
S22	21869	S19 and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:05
S23	5690	S20 and S21 and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:05
S24	5690	S23 and (etch or remove)".ti"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:05
S25	1689	S23 and (etch or "remove.ti")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:06
S26	47	S23 and (etch.ti. or "remove.ti")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:26
S27	1032	S23 and etchant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:06
S28	13	S26 and (metal near oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:46

S29	0	S26 and (high near (constant or k or permittivity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:45
S30	0	S26 and (high near (k or constant) near dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 12:45
S31	32	S26 and dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 14:52
S32	3	09/340669	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 14:30
S33	2	"6453914".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 14:59
S34	2	"6764552".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:02
S35	17	"4345969"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:02
S37	116	bulkhead near configuration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 13:42
S38	15	S37 and apparatus and environment	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 13:44
S39	154	apparatus and P5000	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB		ON	2006/04/05 13:54

S40	55	SEMIX	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 13:56
541	6	S40 and SOG	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 13:54
S42	25	S40 and apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:01
S43	4392569	apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:01
S45	26381	bulkhead	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:01
S46	7513	S43 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:01
S47	3444	internal near environment	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:24
S48	14	S46 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:01
S49	2	S48 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:04
S50	0	internal near laminar near air near flow	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:03

		LAST Scare	,			
S51	2314	laminar near air near flow	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:40
S52	1999519	internal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:03
S53	882	S51 and S52	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:03
S54	465	S43 and S53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:03
S55	1640037	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:04
S56	162	S54 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:08
S57	4402	implanter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:11
S58	6	S57 and S51	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:11
S59	1068	S51 and S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:23
S60	17682	environment\$3 near control	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:24

S61	30	S59 and S60	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:31
S62	15	install\$2 near chase	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:32
S63	0	cleanroom near partition near wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:33
S64	71833	partition near wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:32
S65	1498	cleanroom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:33
S66	11	S64 and S65	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 14:35
S67	0	from clean room to apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:36
S68	0	clean room to apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:36
S69	492	clean room apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:36
S70	44	S69 and hepa	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:43

		LASI Searc	ii iijscoi y			
S71	3444	internal environment	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:43
S72	1685	S71 and S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:44
S73	304	S72 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:50
S74	0	anelva loader	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:50
S75	3770	anelva	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:50
S76	16	S75 and loader	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:51
S77	0	S76 and hepa	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:51
S78	57	automatic and loader and hepa	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:54
S79	1	(automatic near loader) and hepa	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:52
S80	45	(bulkhead near mount) and apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:55

		LAST Scare	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,			
S81	1	S80 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 14:56
S82	111987	method and install	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:45
S83	1077	method near install	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:39
S84	6209858	equipment or tool or apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:45
S85	40969	(laminar near air near flow) or (environment\$3 near control\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:40
S86	26381	bulkhead	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:41
S87	8	S83 and S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:41
S88	648	S83 and S84	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:42
S89	6	S85 and S88	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:42
S90	52	S88 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:42

		EAST Scare	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,			
S91	222432	semiconductor same (equipment or tool or apparatus)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:46
S92	20887	method same install	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:46
S93	24	S91 and S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:46
594	409	S91 and S92	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:47
S95	9091385	(method or install or installation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:47
S96	20106	(method) near (install or installation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:49
S97	6209858	tool or equipment or apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:48
S98	1498	cleanroom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:48
S99	4	S96 and S97 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:48
S10 0	949243	(install or installation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:49

			-			
S10 1	27758	S100 near S97	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:49
S10 2	9	S101 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:56
S10 3	718	52/281	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:56
S10 4	1252	52/79.1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:57
S10 5	1539	29/25.01	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:57
S10 6	214	98/33.1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:58
S10 7	22687	chase	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:58
S10 8	333741	partition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:58
S10 9	78	S101 and S107	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:59
S11 0	957	S101 and S108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:59

S11 1	3	S109 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:00
S11 2	82	S110 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 15:59
S11 3	201	29/25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:00
S11 4	100	cleanroom.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:11
S11 5	3	"5692978"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:12
S11 6	2	"5642978".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:13
S11 7	2	"4667579".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:16
S11 8	41	cmp and bulkhead	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:24
S11 9	0	(chemical adj mechnical adj polish) and chase	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:24
S12 0	0	(chemical adj mechnical adj polish) and install	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:26

S12 1	2	cleanroom equipment and install	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:26
S12 2	530	mirra	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:26
S12 3	0	(chemical adj mechnical adj polish)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:26
S12 4	7258	(chemical adj mechanical adj polish)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:26
S12 5	21	S124 and install	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:28
S12 6	0	S125 and hepa	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/04/05 16:26